IEC 61249-2-51

Edition 1.0 2023-05

INTERNATIONAL STANDARD

NORME INTERNATIONALE

Materials for printed boards and other interconnecting structures – Part 2-51: Reinforced base materials, clad and unclad – Base materials for integrated circuit card carrier tape, unclad

Matériaux pour circuits imprimés et autres structures d'interconnexion – Partie 2-51: Matériaux de base renforcés, plaqués et non plaqués – Matériaux de base pour bande support de carte à circuit intégré, non plaqués



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MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

Part 2-51: Reinforced base materials clad and unclad – Base materials for integrated circuit card carrier tape, unclad

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1847/FDIS	91/1865/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 61249 series, published under the general title *Materials for printed boards and other interconnecting structures*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

Part 2-51: Reinforced base materials clad and unclad – Base materials for integrated circuit card carrier tape, unclad

1 Scope

This part of IEC 61249 specifies the construction, materials, property requirements, quality assurance, packaging, marking, storage of base materials for integrated circuit card carrier tape, unclad (hereinafter referred to as IC carrier tape base materials).

This document is applicable to IC carrier tape base materials, which is a glue-coated material, one side is woven E-glass reinforced epoxy underlayer, and the other side is coated with adhesive and protected by release film.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61189-2:2006, *Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 2: Test methods for materials and other interconnection structures*

IEC PAS 61249-6-3, *Specification for finished fabric woven from "E" glass for printed boards*

ISO 2813, *Paints and varnishes – Determination of gloss value at 20°, 60° and 85°*

ISO 8296, *Plastics – Film and sheeting – Determination of wetting tension*

ISO 11014:2009, *Safety data sheet for chemical products – Content and order of sections*

ISO 21920-2, *Geometrical product specifications (GPS) – Surface texture: Profile – Part 2: Terms, definitions and surface texture parameters*

ASTM D882, *Standard Test Method for Tensile Properties of Thin Plastic Sheeting*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

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